

# CS35L36A Schematic and Layout Guidelines

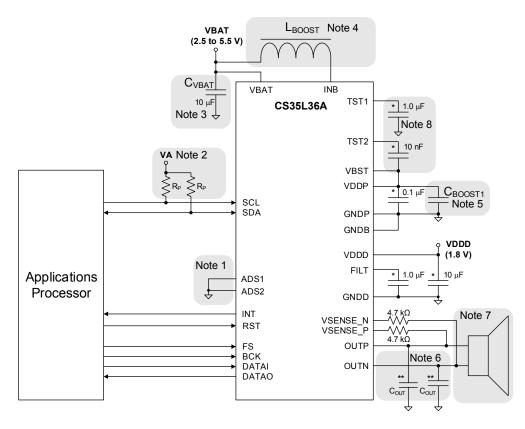
#### 1 Introduction

This document describes the schematic and layout guidelines for the CS35L36A amplifier.

All layout recommendations are preliminary and may be updated in future revisions of this document.

#### 2 Schematic Reference

The schematic below corresponds to a basic configuration for the amplifier.



# 2.1 Schematic Suggestions - Component Selection

- 1. This shows one example of how to configure the 7-bit I<sup>2</sup>C address. The I<sup>2</sup>C address is set as 0x50 in this case.
- Minimum R<sub>P</sub> value is determined from the maximum VDDD level, the minimum sink current strength of their respective output, and the
  maximum low-level output voltage (V<sub>OL</sub>). Maximum R<sub>P</sub> values may be determined by how fast their associated signals must transition, taking
  into account load capacitance.
- 3. Place the 10- $\mu\text{F}$  bulk capacitor close to the  $L_{BOOST}$  inductor.
- 4. Boost converter L<sub>BOOST</sub> inductor values of 2.2 to 1.0 μH are supported for typical use operation. However, the selected L<sub>BOOST</sub> inductor must not derate to a value of less than 0.7 μH during normal use to maintain proper loop stability.
- 5. The boost converter C<sub>BOOST</sub> capacitors are recommended to have a maximum voltage rating of at least 10 V and must not derate to a combined capacitance value of less than 3.6 μF when 10.0 VDC is applied across the capacitors. Note that ceramic capacitors can derate considerably when a DC voltage is applied to them. The total derated C<sub>BOOST</sub> capacitance at 10.0 VDC must not exceed 58 μF.
- 6. The C<sub>OUT</sub> capacitors are optional EMI suppressors that are used depending on the application requirements. It is recommended that the value of these components not exceed 2 nF, as switching losses increase linearly with increases to these capacitances.
- 7. When using a simulated speaker load of 8  $\Omega$  + 33  $\mu$ H, a Coilcraft DO5040H-333MLB inductor is used.
- 8. Presence of capacitors on TST1 and TST2 pins impart no functionality during normal operation. They may be omitted and are completely optional.

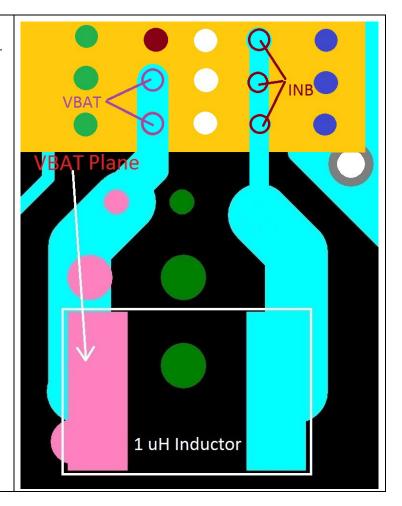




# 3 Layout Suggestions

## 3.1 VBAT Routing

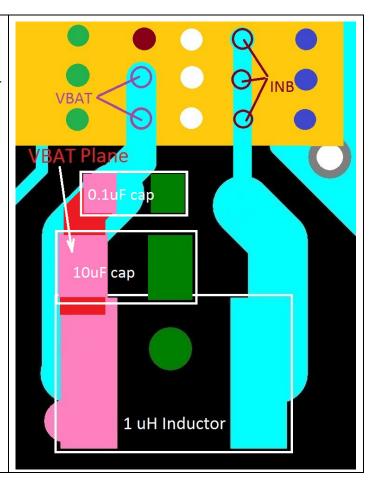
- 1. Use a power plane for VBAT delivery.
- 2. Connect VBAT to the inductor with multiple vias.
- 3. The VBAT pins (C1, C2) should drop down directly to the VBAT plane through vias.
- Use wide (~25 mil) and as short as possible traces to connect the inductor to the INB node (E1, E2, E3).





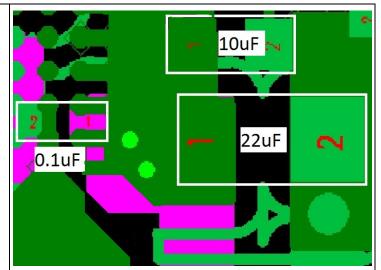
### 3.2 VBAT Decoupling

- 1. Place a 0.1 μF capacitor as close to the VBAT pins (C1, C2) as possible.
- Place a 10 μF CVBAT capacitor as close to the inductor connection to the VBAT supply as possible. Depending on the available board space, it may be placed on either side of the board.



## 3.3 VBST Routing

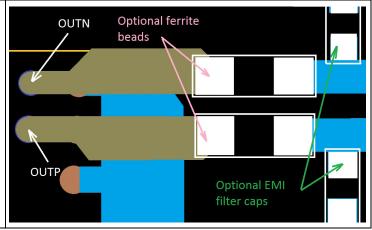
- 1. Place a 0.1 µF CBOOST(OUT) bypass cap as close to the VBST pins (F1, F2, F3) as possible.
- 2. Place larger CBOOST(OUT) bypass caps (22  $\mu$ F and 10  $\mu$ F) close to VBST pads.
- 3. Tie all VBST/VDDP pins together (F1 through F6) by a 5 mil wide trace and come out to a wider ~25 mil trace for the large bypass caps.





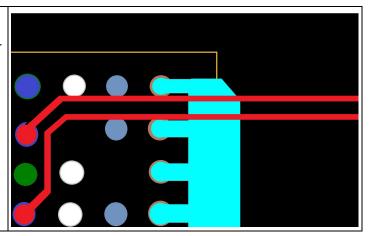
### 3.4 Speaker Routing

- 1. OUTP and OUTN traces should be as symmetrical as possible.
- 2. Bring out signals on inner layer and come up to top layer.
- 3. Maintain 30-40 mil trace width as traces go out to the SPKR pads.
- 4. Maintain distance from VBST/VDDP before bringing traces up to the top layer.
- 5. Have GND shield around output traces to avoid noise coupling.



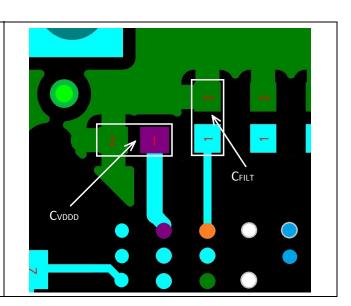
#### 3.5 VSENSE Routing

- Run 5 mil or wider VSENSE\_P and VSENSE\_N traces differentially between VSENSE\_P, VSENSE\_ N pads and the output side of the EMI filter (speaker side).
- 2. Provide GND shielding around VSENSE\_P and VSENSE\_N traces to minimize noise coupling from the Class-D outputs.
- An RC filter may be optionally added to the VSENSE\_P and VSENSE\_N lines for output EMI filtering.



## 3.6 Miscellaneous Routing

- 1. Place the FILT decoupling capacitor as close as possible to pad C6.
- 2. Place the VDDD decoupling capacitor as close as possible to pad B6.
- 3. All ground pins need to be connected to the same ground plane.





## 4 Revision History

#### Table 4-1. Revision History

| Revision | Change            |
|----------|-------------------|
| R1       | Initial revision. |
| SEP '17  |                   |

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